
[Upgrade to revision]
RX23W Group
BLE Module Firmware Integration Technology Rev.2.40

R20TS0865EJ0100
Rev.1.00
Jul. 01, 2022

Outline

RX23W Group BLE Module Firmware Integration Technology (FIT) has been updated from Rev.2.31 to Rev.2.40.

Since the `R_BLE_Open` API has been modified, please upgrade the revision if you are using this FIT module.

1. Products to Be Updated

RX23W Group BLE Module Firmware Integration Technology
Rev.1.00, 1.01, 1.10, 2.00, 2.10, 2.11, 2.20, 2.30, 2.31

2. Description

The main change is as follows. Refer to the Application Note's Revision History for other changes.

[RX23W Group BLE Module Firmware Integration Technology Application Note](#)

2.1 Issue Fixed

2.1.1 Adjustment of Initialization Stability Wait Time of `R_BLE_Open`

There was an issue that H/W initialization error occurred in the initialization process of the `R_BLE_Open` API depending on the conditions when power was applied, and the `r_ble_rf_control_error` function was called with `err_no` "0xFF04". As a modification of this issue, the stable waiting time of the initialization process in `R_BLE_Open` has been adjusted. This modification will increase the processing time of `R_BLE_Open` by about 200msec.

2.1.2 Stabilization of peripheral communication operation when Connection Latency is enabled

Fixed an issue when the RX23W is a peripheral role and the connection latency is non-zero, data transmission timing on the RX23W side rarely goes out of sync with the central device, causing a delay in data transmission until the RX23W resynchronization.

2.1.3 Fixed an issue the bonding information in the data flash cannot be deleted

Fixed an issue that the remaining bonding information cannot be deleted due to incorrect references to the bonding information in the data flash after using the `R_BLE_SECD_DelRemKeys` API with specified BD address to delete a bonding information set when two or more bonding information sets are registered.

3. Updating the Product

Download the FIT module using the RX Smart Configurator and update the software component version.

For details, visit the following web site and refer to the RX Smart Configurator User's Guide.

[Firmware Integration Technology \(FIT\) | Renesas](#)

Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Jul.01.22	-	First edition issued

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